



NEWS RELEASE

SiSoft Receives DesignCon Best Paper Award at DesignCon 2015

Best Paper Recognition in Interconnect Design and Test Category

MAYNARD, MA – January 29, 2015 -- Signal Integrity Software Inc. (SiSoft) today announced it has received a "Best Paper Award" for one of the papers it presented at DesignCon 2014. The paper, titled, "Moving Higher Data Rate Serial Links into Production – Issues and Solutions", was awarded in the Interconnect Design & Test category. The DesignCon Best Paper Awards took place Wednesday at DesignCon 2015 which is being held January 27-30, 2015, at the Santa Clara Convention Center.

According to DesignCon, "DesignCon Paper Awards recognize outstanding contributions to the educational goals of the DesignCon program. Papers are judged both on the merits of the written document and on the quality of their presentation at DesignCon 2014. The awards serve to acknowledge the authors who receive them as leading practitioners in semiconductor and electronic design."

"Moving Higher Date Rate Serial Links into Production – Issues and Solutions" examines the variety of issues encountered when large systems move thousands of higher data rate (12 to 25 (Gbps) channels into production. Many of these issues were not seen in the first three generations of serial links. This paper describes issues and solutions recently discovered in bringing 4th generation products into the mainstream. Solutions are substantiated using simulation, field solution, VNA/TDR/Scope measurement, and photomicrography of fabricated structures.

"High quality technical papers are a hallmark of DesignCon; therefore, the Best Paper Award is very competitive. My congratulations to the SiSoft authors for being part of a team that won a DesignCon Best Paper Award in the Interconnect Design & Test category," said DesignCon Technical Program Director, Janine Love. "The award is a unique honor that recognizes papers as well as their accompanying presentations for their quality, relevance, impact, originality, and content."

About SiSoft

SiSoft collaborates with customers and their suppliers to develop innovative solutions to the world's toughest high-speed design problems. SiSoft accelerates design cycles through a combination of award-winning EDA simulation software, methodology training and consulting services. Quantum Channel Designer (QCD) is the

Industry's Premier Channel Simulator for the design and analysis of Multi-Gigabit serial links and a DesignVision Award Winner. Quantum-SI (QSI) is the leading solution for integrated signal integrity, timing and crosstalk analysis of high-speed parallel interfaces. SiSoft's products automate comprehensive pre- and post-route analysis of high speed interfaces, detailing a design's operating voltage and timing margins. More information on SiSoft can be found at www.sisoft.com.

About DesignCon

DesignCon, produced by UBM Tech, is the world's premier conference for chip, board and systems design engineers in the high-speed communications and semiconductor communities. DesignCon, created by engineers for engineers, takes place annually in Silicon Valley and remains the largest gathering of chip, board and systems designers in the country. This four-day technical conference and expo combines technical paper sessions, tutorials, industry panels, product demos and exhibits from the industry's leading experts and solutions providers. More information is available at: www.designcon.com/santaclara

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